

# **TBB1016**

# Twin Built in Biasing Circuit MOS FET IC VHF/VHF RF Amplifier

REJ03G1327-0200 Rev.2.00 Aug 22, 2006

### **Features**

- Small SMD package CMPAK-6 built in twin BBFET; To reduce using parts cost & PC board space.
- Very useful for total tuner cost reduction.
- Suitable for World Standard Tuner RF amplifier.
- High gain; PG = 32 dB at 200 MHz
- Low noise; NF = 1.0 dB at 200 MHz
- Power supply voltage: 5 V

## Outline

Notes:

RENESAS Package code: PTSP0006JA-A (Package name: CMPAK-6)



1. Drain(1) 2. Source 3. Drain(2) 4. Gate-1(2) 5. Gate-2 6. Gate-1(1)

1. Marking is "RM".

2. TBB1016 is indivisual type number of RENESAS TBBFET.

## **Absolute Maximum Ratings**

			$(Ta = 25^{\circ}C)$
Item	Symbol	Ratings	Unit
Drain to source voltage	V <sub>DS</sub>	6	V
Gate1 to source voltage	V <sub>G1S</sub>	+6	V
		-0	
Gate2 to source voltage	V <sub>G2S</sub>	+6	V
		-0	
Drain current	I <sub>D</sub>	30	mA
Channel power dissipation	Pch <sup>Note3</sup>	250	mW
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Note: 3. Value on the glass epoxy board (50 mm  $\times$  40 mm  $\times$  1 mm)

# **Electrical Characteristics**

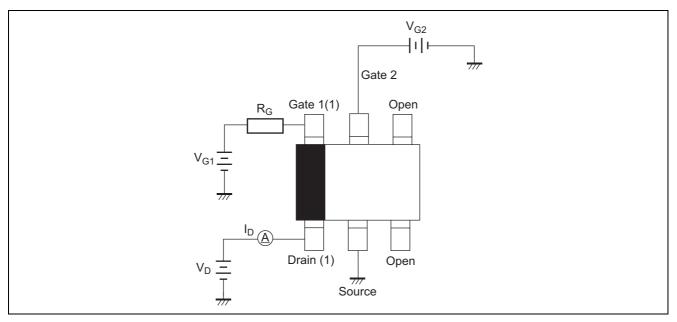
# • The below specification are applicable for FET1 and FET2 unit

						(Ta = 25°C)
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V <sub>(BR)DSS</sub>	6	—	—	V	$I_D = 200 \ \mu A, \ V_{G1S} = V_{G2S} = 0$
Gate1 to source breakdown voltage	V <sub>(BR)G1SS</sub>	+6	—	—	V	$I_{G1}$ = +10 µA, $V_{G2S}$ = $V_{DS}$ = 0
Gate2 to source breakdown voltage	V <sub>(BR)G2SS</sub>	+6	—	—	V	$I_{G2}$ = +10 µA, $V_{G1S}$ = $V_{DS}$ = 0
Gate1 to source cutoff current	I <sub>G1SS</sub>	_	—	+100	nA	$V_{G1S} = +5 V, V_{G2S} = V_{DS} = 0$
Gate2 to source cutoff current	I <sub>G2SS</sub>	_	—	+100	nA	$V_{G2S}$ = +5 V, $V_{G1S}$ = $V_{DS}$ = 0
Gate1 to source cutoff voltage	V <sub>G1S(off)</sub>	0.5	0.8	1.1	V	$V_{DS} = 5 \text{ V}, V_{G2S} = 4 \text{ V}, I_D = 100 \ \mu\text{A}$
Gate2 to source cutoff voltage	V <sub>G2S(off)</sub>	0.4	0.7	1.0	V	$V_{DS} = 5 \text{ V}, V_{G1S} = 5 \text{ V}, I_D = 100 \ \mu\text{A}$
Drain current	I <sub>D(op)</sub>	11	15	19	mA	
Forward transfer admittance	y <sub>fs</sub>	30	35	42	mS	$V_{DS} = 5 \text{ V}, V_{G1} = 5 \text{ V}, V_{G2S} = 4 \text{ V},$ f = 1 kHz, R <sub>G</sub> = 120 k $\Omega$
Input capacitance	Ciss	1.8	2.2	2.6	pF	$V_{DS} = 5 V, V_{G1} = 5 V, V_{G2S} = 4 V,$
Output capacitance	Coss	0.9	1.3	1.7	pF	f = 1 MHz, $R_G$ = 120 kΩ
Power gain	PG	27	32	37	dB	$V_{DS} = 5 V, V_{G1} = 5 V, V_{G2S} = 4 V,$
Noise figure	NF	—	1.0	1.7	dB	$R_{G} = 120 \text{ k}\Omega, \text{ f} = 200 \text{ MHz}$

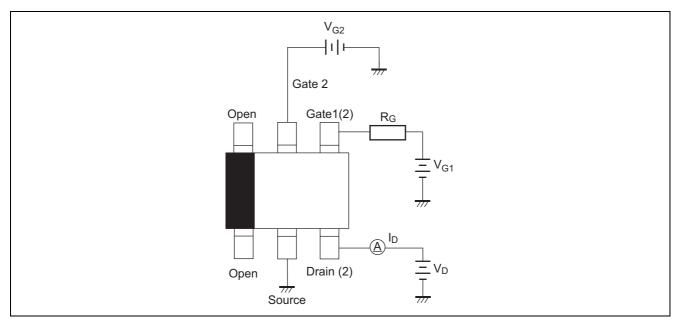


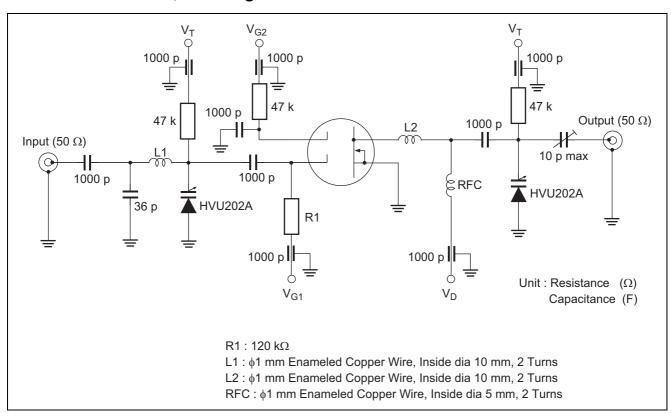
# DC Biasing Circuit for Operating Characteristic Items ( $I_{D(op)}$ , $|y_{fs}|$ , Ciss, Coss, NF, PG)

Measurement of FET1



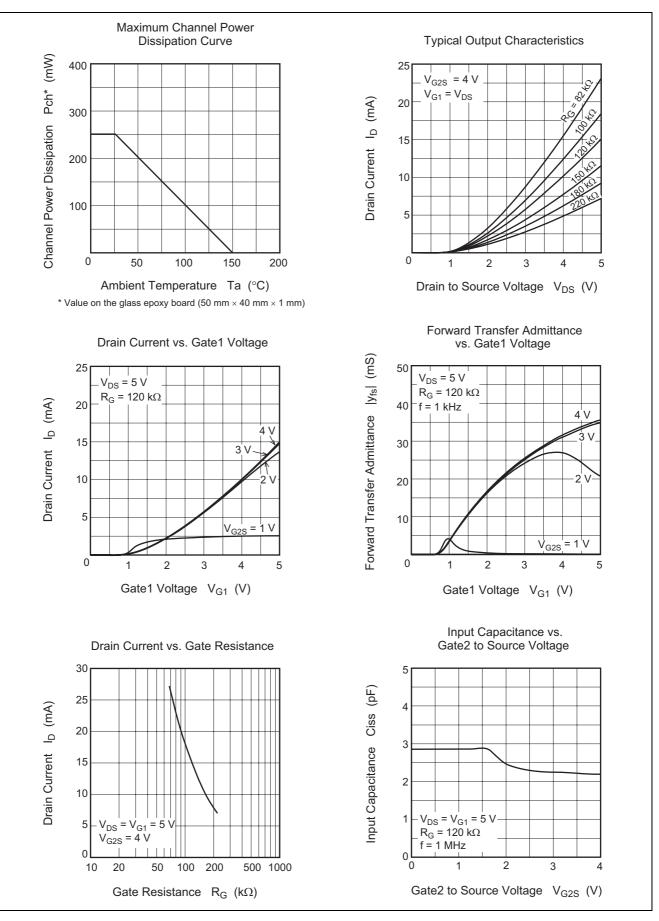
### • Measurement of FET2



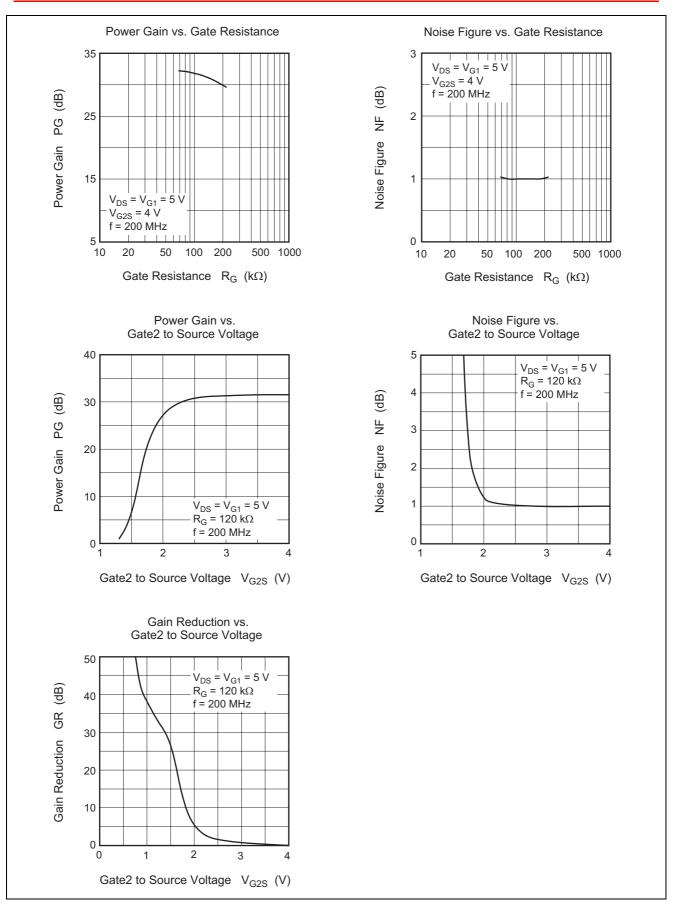


# 200 MHz Power Gain, Noise Figure Test Circuit

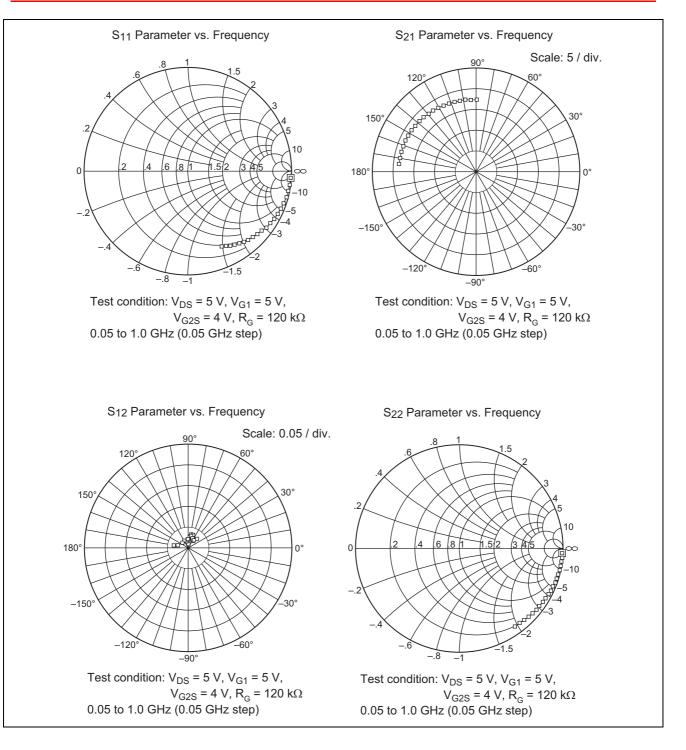
### **Main Characteristics**









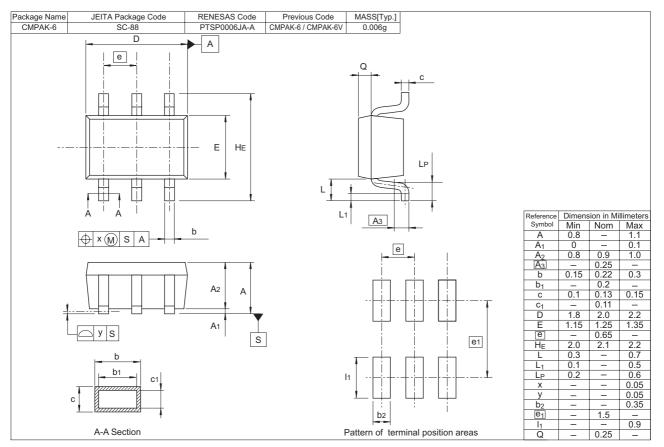


# S parameter

$(V_{DS} = 5 V, V_{G1} = 5 V, V_{G2S} = 4 V, R_G = 120 k\Omega, Zo = 50$
--

Freq.	S	11	S	21	S	12	S	22
(MHz)	Mag	Deg	Mag	Deg	Mag	Deg	Mag	Deg
50	0.994	-3.7	3.73	175.3	0.002	88.4	0.992	-2.4
100	0.992	-7.6	3.72	170.7	0.003	107.7	0.996	-5.1
150	0.987	-11.1	3.72	166.1	0.004	54.7	0.992	-7.2
200	0.985	-14.8	3.70	161.7	0.004	62.4	0.990	-9.6
250	0.975	-18.6	3.71	157.0	0.005	81.1	0.990	-12.0
300	0.967	-21.9	3.69	152.9	0.005	83.3	0.984	-14.6
350	0.960	-25.4	3.68	148.1	0.004	65.3	0.982	-17.1
400	0.952	-28.9	3.65	143.8	0.006	68.8	0.982	-19.4
450	0.940	-32.2	3.64	138.9	0.006	77.6	0.972	-21.9
500	0.934	-35.7	3.62	134.7	0.006	69.3	0.971	-24.6
550	0.914	-38.8	3.58	130.0	0.006	77.0	0.965	-26.9
600	0.904	-42.1	3.58	125.9	0.006	45.7	0.959	-29.9
650	0.892	-45.4	3.55	121.4	0.005	66.8	0.955	-32.5
700	0.881	-48.8	3.52	116.9	0.004	52.5	0.948	-35.6
750	0.870	-51.5	3.51	112.5	0.004	93.5	0.949	-38.3
800	0.855	-54.4	3.49	107.9	0.004	92.7	0.941	-41.4
850	0.839	-57.5	3.47	103.7	0.004	121.0	0.936	-44.4
900	0.827	-60.3	3.48	99.3	0.004	140.2	0.929	-47.7
950	0.809	-62.8	3.43	95.0	0.005	167.7	0.921	-50.9
1000	0.796	-65.7	3.43	90.3	0.007	171.4	0.921	-54.5

# **Package Dimensions**



# **Ordering Information**

Part Name	Quantity	Shipping Container
TBB1016RMTL-E	3000 pcs	

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

# Renesas Technology Corp. sales Strategic Planning Div. Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan

Keep safety first in your circuit designs! 1. Renesas Technology Corp. puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage. Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

- Notes regarding these materials
  1. These materials are intended as a reference to assist our customers in the selection of the Renesas Technology Corp. product best suited to the customer's application; they do not convey any license under any intellectual property rights, or any other rights, belonging to Renesas Technology Corp. or a third party.
  2. Renesas Technology Corp. assumes no responsibility for any damage, or infringement of any third-party's rights, originating in the use of any product data, diagrams, charts, programs, algorithms, or circuit application examples contained in these materials.
  3. All information contained in these materials, including product data, diagrams, charts, programs and algorithms represents information on products at the time of publication of these materials, and are subject to change by Renesas Technology Corp. without notice due to product improvements or other reasons. It is therefore recommended that customers contact Renesas Technology Corp. or an authorized Renesas Technology Corp. product distributor for the latest product information before purchasing a product listed herein.
  The information described here may contain technical inaccuracies or typographical errors. Renesas Technology Corp. asyumes no responsibility for any damage, liability, or other loss rising from these inaccuracies or errors. Please also pay attention to information published by Renesas Technology Corp. by various means, including the Renesas Technology Corp. Semiconductor home page (http://www.renesas.com).
  4. When using any or all of the information contained in these materials, including product data, diagrams, charts, programs, and algorithms, please be sure to

- Nonne page (http://www.renessas.com).
  4. When using any or all of the information contained in these materials, including product data, diagrams, charts, programs, and algorithms, please be sure to evaluate all information as a total system before making a final decision on the applicability of the information and products. Renesas Technology Corp. assumes no responsibility for any damage, liability or ther loss resulting from the information contained herein.
  5. Renesas Technology Corp. semiconductors are not designed or manufactured for use in a device or system that is used under circumstances in which human life is potentially at stake. Please contact Renesas Technology Corp. or an authorized Renesas Technology Corp. product distributor when considering the use of a product contained herein for any specific purposes, such as apparatus or systems for transportation, vehicular, medical, aerospace, nuclear, or undersea repeater use.
- use. 6. The prior written approval of Renesas Technology Corp. is necessary to reprint or reproduce in whole or in part these materials. 7. If these products or technologies are subject to the Japanese export control restrictions, they must be exported under a license from the Japanese government and cannot be imported into a country other than the approved destination. Any diversion or reexport contrary to the export control laws and regulations of Japan and/or the country of destination is prohibited. 8. Please contact Renesas Technology Corp. for further details on these materials or the products contained therein.



### **RENESAS SALES OFFICES**

Refer to "http://www.renesas.com/en/network" for the latest and detailed information.

Renesas Technology America, Inc. 450 Holger Way, San Jose, CA 95134-1368, U.S.A Tel: <1> (408) 382-7500, Fax: <1> (408) 382-7501

Renesas Technology Europe Limited Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K. Tel: <44> (1628) 585-100, Fax: <44> (1628) 585-900

Renesas Technology (Shanghai) Co., Ltd. Unit 204, 205, AZIACenter, No.1233 Lujiazui Ring Rd, Pudong District, Shanghai, China 200120 Tel: <86> (21) 5877-1818, Fax: <86> (21) 6887-7898

Renesas Technology Hong Kong Ltd. 7th Floor, North Tower, World Finance Centre, Harbour City, 1 Canton Road, Tsimshatsui, Kowloon, Hong Kong Tel: <852> 2265-6688, Fax: <852> 2730-6071

Renesas Technology Taiwan Co., Ltd. 10th Floor, No.99, Fushing North Road, Taipei, Taiwan Tel: <886> (2) 2715-2888, Fax: <886> (2) 2713-2999

Renesas Technology Singapore Pte. Ltd. 1 Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632 Tel: <65> 6213-0200, Fax: <65> 6278-8001

Renesas Technology Korea Co., Ltd. Kukje Center Bldg. 18th Fl., 191, 2-ka, Hangang-ro, Yongsan-ku, Seoul 140-702, Korea Tel: <82> (2) 796-3115, Fax: <82> (2) 796-2145

Renesas Technology Malaysia Sdn. Bhd Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No.18, Jalan Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia Tel: <603> 7955-9390, Fax: <603> 7955-9510

### http://www.renesas.com